



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-01-17
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	GIUSEPPE VITALI PALMA	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FDO7*0922BS6	A	BO2A	2013-01-17
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	ium/Gold (Ni/Pd/Au) Tin/Bismuth (S	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	PACKAGE: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FDO7*0922856					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.32	mg	supplier	die	Silicon (Si)	7440-21-3		1.311	mg	993182	16388
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	6818	113
Leadframe	Copper & its alloys	34.379	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.256	mg	996422	428200
						Iron (Fe)	7439-89-6		0.016	mg	465	200
						Iron Phosphide (FeP)	26508-33-8		0.029	mg	844	363
				supplier	metallization	Nickel (Ni)	7440-02-0		0.071	mg	2065	888
						Palladium (Pd)	7440-05-3		0.005	mg	145	63
						Gold (Au)	7440-57-5		0.002	mg	58	25
Die attach	Other Organic Materials	0.385	mg	supplier	glue	Silver (Ag)	7440-22-4		0.289	mg	750649	3613
						Epoxy Cresol Novolak	29690-82-2		0.095	mg	246753	1188
						1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.001	mg	2597	13
Bonding wire	Other inorganic materials	0.116	mg	supplier	wire	Gold (Au)	7440-57-5		0.116	mg	1000000	1450
encapsulation	Other Organic Materials	43.8	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.38	mg	100000	54750
						phenol resin	9003-35-4		2.19	mg	50000	27375
						Carbon Black	1333-86-4		0.438	mg	10000	5475
						Silica, vitreous	60676-86-0		35.04	mg	800000	438000
						Antimony Trioxide	1309-64-4		0.876	mg	20000	10950
				JIG I	mold compound	Brominated epoxy resin	68928-70-1		0.876	mg	20000	10950